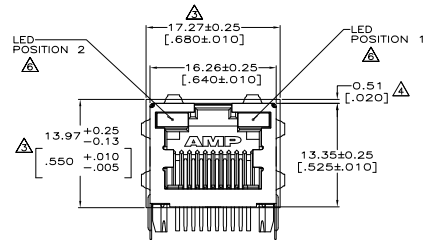
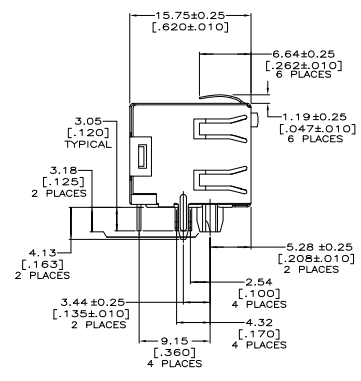
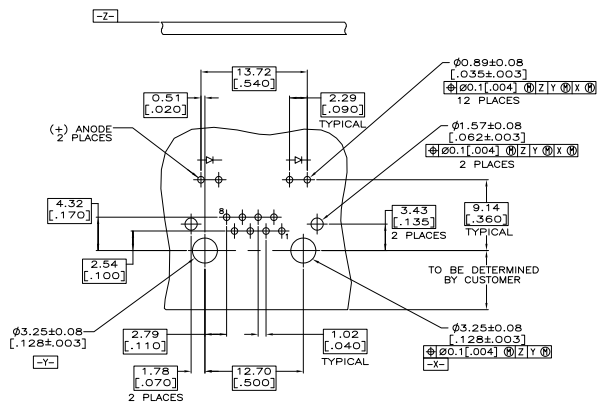


REV	DATE	DESCRIPTION	BY	CHK	APP
AA	22				
A		REV PER EC 0511-0201-04			



- ▲ MATERIAL:  
 HOUSING - HIGH TEMPERATURE THERMOPLASTIC, BLACK, UL94V-0.  
 TERMINALS - 0.36[.014] THICK PHOS BRONZE PLATED WITH 3.8 $\mu$ m[.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA. 1.27 $\mu$ m[.000050] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27 $\mu$ m[.000050] MINIMUM THICK NICKEL.  
 SHIELD - 0.196[.0077] THICK COPPER ZINC ALLOY PREPLATED WITH 1.27 $\mu$ m[.000050] MINIMUM SATIN NICKEL WITH 2.03 $\mu$ m[.000080] MINIMUM TIN POST DIPPED ON PCB GROUND TABS.  
 LIGHT EMITTING DIODE (LED) - DIFFUSED EPOXY LENS, 0.51 x 0.51[.020 x .020] CARBON STEEL WIREFRAME LEADS PREPLATED WITH 8.89 $\mu$ m[.0003500] THICK Sn/Cu OVER 2.03 $\mu$ m[.000080] THICK Ag OVER 1.02 $\mu$ m[.000040] THICK Cu OVER 3.56 $\mu$ m[.000140] THICK Ni OVER 1.02 $\mu$ m[.000040] Cu UNDERPLATE.
- JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
  - SUGGESTED PANEL OPENING DIMENSIONS.
  - SUGGESTED CLEARANCE BETWEEN TOP OF CONNECTOR AND TOP PANEL OPENING.
  - 0.051[.002] WHITE POLYESTER INSULATOR APPLIED TO BACK OF HOUSING.
  - SEE TABLE FOR COLOR OF LEDS AND NUMBER REQUIRED.
  - THIS MODULAR JACK WITH INTEGRATED LED IS NOT IR REFLOW SOLDERING PROCESS COMPATIBLE.



SUGGESTED PRINTED CIRCUIT BOARD LAYOUT  
 (COMPONENT SIDE)

INDICATOR COLOR	POSITION 2	POSITION 1	PART NUMBER
GREEN	GREEN	GREEN	6116173-5
GREEN	YELLOW	GREEN	6116173-4
YELLOW	GREEN	GREEN	6116173-1

THIS DRAWING IS A CONTROLLED DOCUMENT

DESIGNED BY	APPROVED BY	DATE	REV
DRN	DRN	108-1163-4	1
REV	REV	114-2154	1

INVERTED MODULAR JACK ASSEMBLY,  
 1X1, SHIELDED, PANEL GROUND,  
 LED, INSULATOR, 120 DEGREE CUTOFF

CUSTOMER DRAWING: A100779G-6116173